

RoHS Compliant Product
 A suffix of "-C" specifies halogen & lead-free

FEATURES

- High Surge Current Capability
- Designed for Surface Mount Application

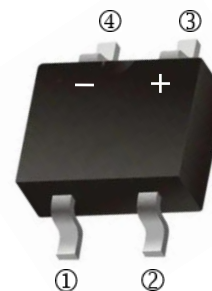
MECHANICAL DATA

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026

MARKING

Part Number	Marking	Part Number	Marking
MB140F-C	MB14F	MB1100F-C	MB110F
MB160F-C	MB16F	MB1200F-C	MB120F

MBF

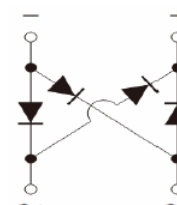


PACKAGE INFORMATION

Package	MPQ	Leader Size
MBF	5K	13 inch

ORDER INFORMATION

Part Number	Type
MB140F-C~MB1200F-C	Lead (Pb)-free and Halogen-free



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating 25°C ambient temperature unless otherwise specified. Single phase half wave 60Hz, resistive or inductive load, For capacitive load current de-rate current by 20%.)

Parameter	Symbol	Part Number				Unit
		MB140F-C	MB160F-C	MB1100F-C	MB1200F-C	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	40	60	100	200	V
Maximum RMS Voltage	V_{RMS}	28	42	70	140	V
Maximum DC Blocking Voltage	V_{DC}	40	60	100	200	V
Maximum Average Forward Current	$I_{F(AV)}$	1				A
Peak Forward Surge Current @8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	40		30		A
Maximum Instantaneous Forward Voltage @ $I_F=1A$	V_F	0.55	0.7	0.85	0.9	V
Maximum DC Reverse Current @Rated DC Blocking Voltage	$T_A=25^{\circ}C$	0.3		0.2	0.1	mA
	$T_A=100^{\circ}C$	10		5	2	
Typical Junction Capacitance ¹	C_J	110	80			pF
Thermal Resistance Junction-Ambient ²	$R_{\theta JA}$	100				°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	125, -55~150				°C

Notes:

1. Measured at 1MHz and applied reverse voltage of 4V D.C.
2. Mounted on glass epoxy PC board with 4x1.5"x1.5" (3.81x3.81 cm) copper pad.

RATINGS AND CHARACTERISTIC CURVES

Fig.1 Forward Current Derating Curve

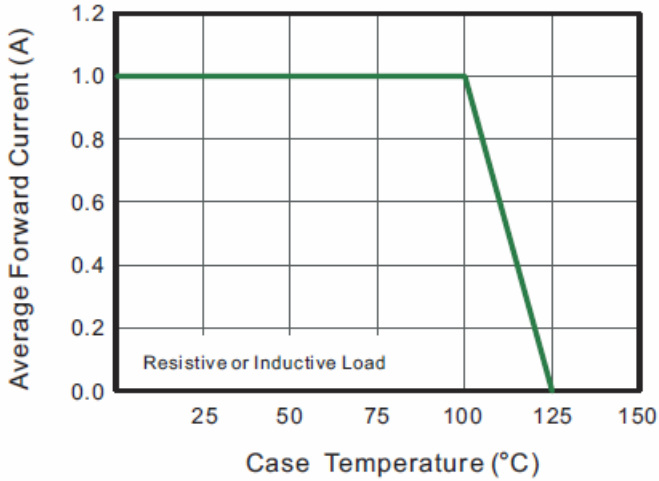


Fig.2 Typical Reverse Characteristics

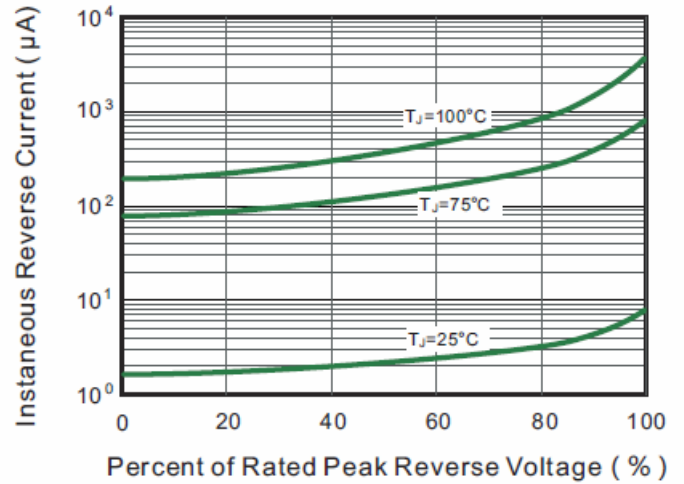


Fig.3 Typical Instantaneous Forward Characteristics

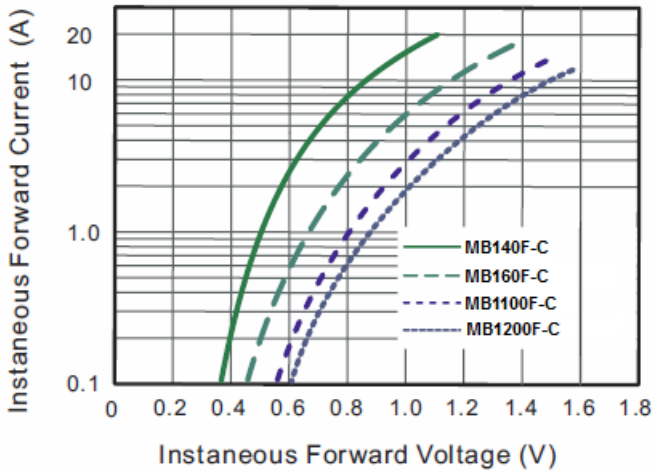


Fig.4 Typical Junction Capacitance

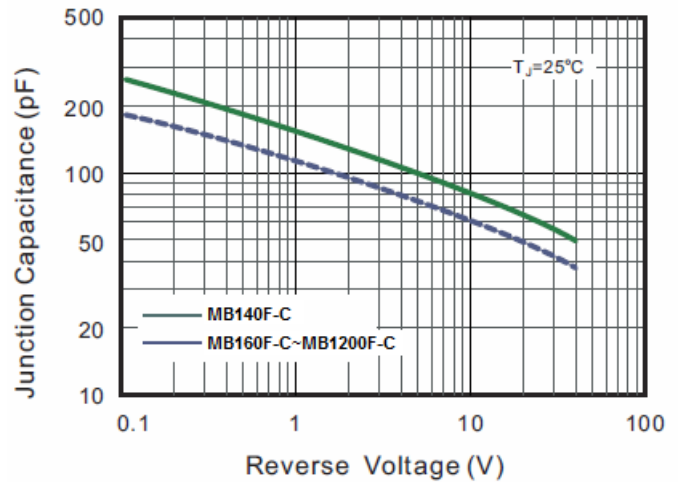


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

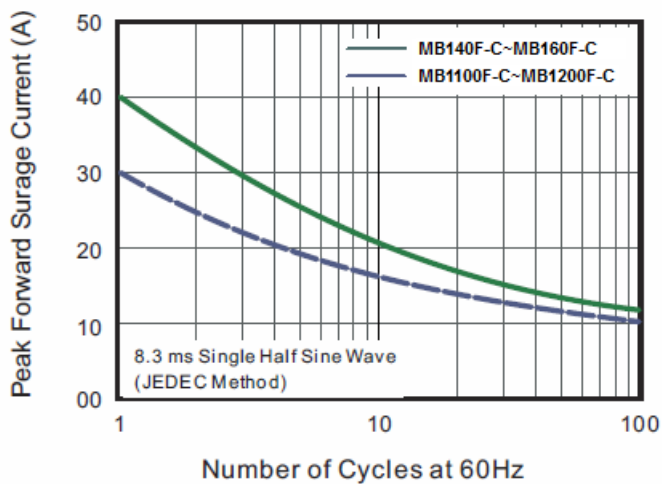
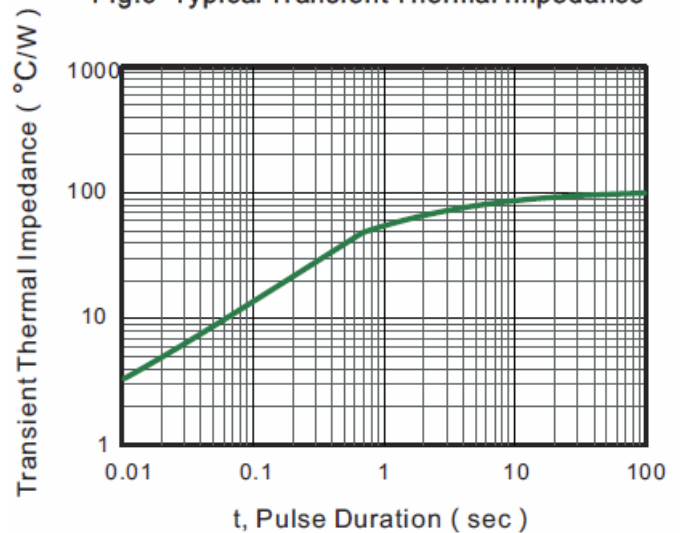
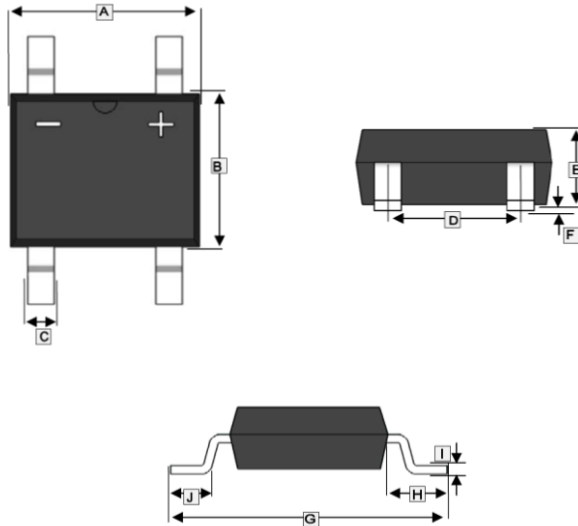


Fig.6- Typical Transient Thermal Impedance



PACKAGE OUTLINE DIMENSION

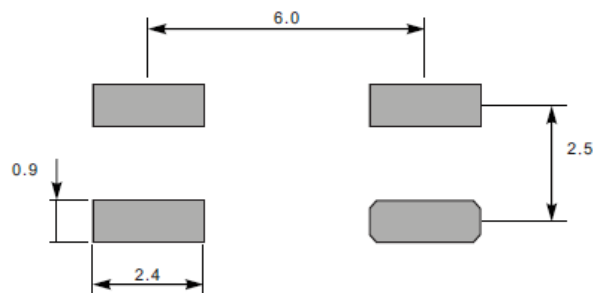
MBF



REF.	Millimeter	
	Min.	Max.
A	4.50	5.00
B	3.60	4.10
C	0.50	0.80
D	2.30	2.70
E	1.20	1.60
F	0.20 TYP.	
G	6.40	7.00
H	1.30	1.70
I	0.15	0.22
J	0.50	1.10

MOUNTING PAD LAYOUT

MBF



*Dimensions in millimeters